

N-Channel MOSFET

Applications:

- Adaptor
- Charger
- .SMPS

Lead Free Package and Finish

V _{DSS}	R _{DS(ON)} (Typ.)	I _D
650V	2.3Ω	5A

Features:

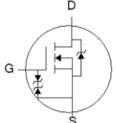
- RoHS Compliant
- Low ON Resistance
- Low Gate Charge
- Peak Current vs Pulse Width Curve
- Inductive Switching Curves

Ordering Information

PART NUMBER	PACKAGE	BRAND					
LSU05N65A	TO-251	IPS					







T_C=25°C unless otherwise specified **Absolute Maximum Ratings**

Symbol	Parameter	LSU05N65A	Units
V_{DSS}	Drain-to-Source Voltage	650	V
I _D	Continuous Drain Current	5	Α
I _{DM}	Pulsed Drain Current, V _{GS} @10V (NOTE *2)	20	Α
D	Power Dissipation	70	W
P _D	Derating Factor above 25℃	0.56	W/℃
V_{GS}	Gate-to-Source Voltage	±20	V
E _{AS}	Single Pulse Avalanche Energy(L=10mH)	150	mJ
E _{AR}	Avalanche Energy ,Repetitive	30	mJ
I _{AR}	Avalanche Current	2.5	Α
VESD(G-S)	Gate to Source ESD(HBM-C=100pF,R=1.5KΩ)	3000	V
TL	Maximum Temperature for Soldering	300	
T _J and T _{STG}	Operating Junction and Storage Temperature Range (NOTE *1)	-55 to150	${\mathbb C}$

Thermal Resistance

Symbol	Parameter	Тур.	Max.	Units	Test Conditions
$R_{\theta,JC}$	Junction-to-Case		1.78		Water cooled heatsink, P _D adjusted for a
000				°C⁄W	peak junction temperature of +150°C.
$R_{\theta JA}$	Junction-to-Ambient		62.5		1 cubic foot chamber, free air.



OFF Characteristics $T_C=25^{\circ}C$ unless otherwise specified

0 = 0 = 0 = 0 = 0 = 0							
Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions	
BV _{DSS}	Drain-to-Source Breakdown Voltage	650			V°C	V_{GS} =0V, I_D =250 μ A	
	Drain-to-Source Leakage Current			1	- μΑ	V _{DS} =650V, V _{GS} =0V	
						T _J =25°C	
I _{DSS}				100		V_{DS} =520V, V_{GS} =0V	
				100		T _J =125℃	
	Gate-to-Source Forward Leakage			+10		V _{GS} =+20V	
I _{GSS}	Gate-to-Source Reverse Leakage			-10	uA	V _{GS} = -20V	

ON Characteristics T_J=25°C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
В	StaticDrain-to-Source		2.3	2.8	Ω	V_{GS} =10V, I_D =2.5A
R _{DS(ON)}	On-Resistance(NOTE *3)		2.3	2.0	12	
$V_{GS(TH)}$	Gate Threshold Voltage	2		4	V	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$
g fs	Forward Transconductance(NOTE *3)		3.5	1	S	V _{DS} =15V, I _D =2.5A

Dynamic Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
C _{iss}	Input Capacitance		560			\/ 0\/\/ 05\/
C _{oss}	Output Capacitance		50		pF	V_{GS} = 0V, V_{DS} = 25V f =1.0MHz
C _{rss}	Reverse Transfer Capacitance		2.2			
Q_g	Total Gate Charge		13			1 54 1/ 5201/
Q_{gs}	Gate-to-Source Charge		2.7		nC	$I_D=5A, V_{DD}=520V$ $V_{GS}=10V$
Q _{gd}	Gate-to-Drain ("Miller") Charge		5.5			v _{GS} = 10V

Resistive Switching Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
t _{d(ON)}	Turn-on Delay Time		14			
t _{rise}	Rise Time		22		no	V_{DD} =325V, I_{D} =5A,
t _{d(OFF)}	Turn-Off Delay Time		29		ns	V_G =10V R_G =10 Ω
t _{fall}	Fall Time		15			

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Source-Drain Diode Characteristics Tc=25℃ unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
	Continuous Source Current			5	Α	
Is	(Body Diode)			3	A	T _C =25℃
1	Maximum Pulsed Current			20	А	
ISM	(Body Diode)					
V_{SD}	Diode Forward Voltage			1.5	V	I_{SD} =5A, V_{GS} =0V
t _{rr}	Reverse Recovery Time		250		ns	I _F = I _S
Q _{rr}	Reverse Recovery Charge		1200		nC	di/dt=100A/us

Notes:

- *1. $T_J = +25^{\circ}C$ to $+150^{\circ}C$.
- *2. Repetitive rating; pulse width limited by maximum junction temperature.
- *3. Pulse width < 380 μ s; duty cycle < 2%.



Test Circuits and Waveforms

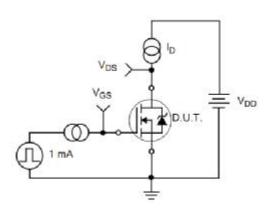


Figure 1. Gate Charge Test Circuit

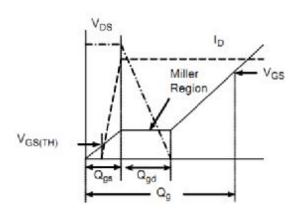


Figure 2. Gate Charge Waveforms

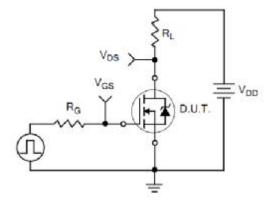


Figure 3. Resistive Switching Test Circuit

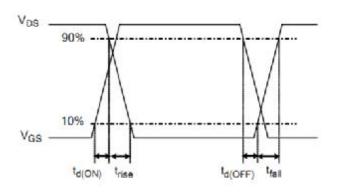
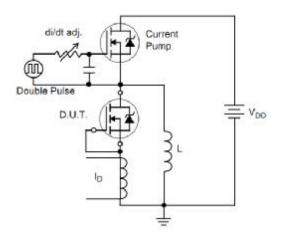


Figure 4. Resistive Switching Waveforms



Test Circuits and Waveforms



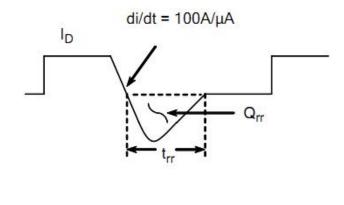


Figure 5. Diode Reverse Recovery Test Circuit

Figure 6. Diode Reverse Recovery Waveform

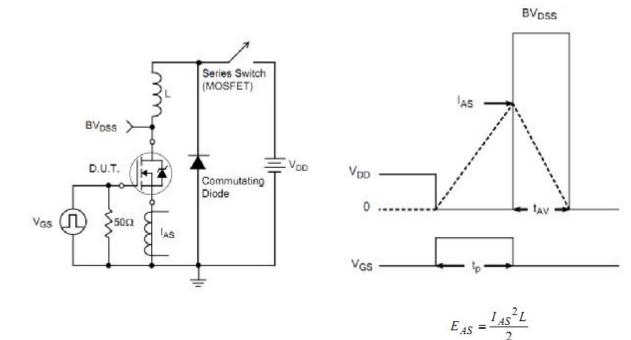


Figure 7. Unclamped Inductive Switching Test Circuit Figure 8. Unclamped Inductive Switching Waveform



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TK31J60W5,S1VQ(O 2SK2614(TE16L1,Q) DMN1017UCP3-7 EFC2J004NUZTDG FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7

NTE2384 NTE2969 NTE6400A DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 SSM6P54TU,LF DMP22D4UFO-7B IPS60R3K4CEAKMA1 DMN1006UCA6-7 DMN16M9UCA6-7 STF5N65M6 STU5N65M6 C3M0021120D DMN13M9UCA6-7

BSS340NWH6327XTSA1 MCM3400A-TP DMTH10H4M6SPS-13 IRF40SC240ARMA1 IPS60R1K0PFD7SAKMA1

IPS60R360PFD7SAKMA1 IPS60R600PFD7SAKMA1